



# GT25FF120B3H

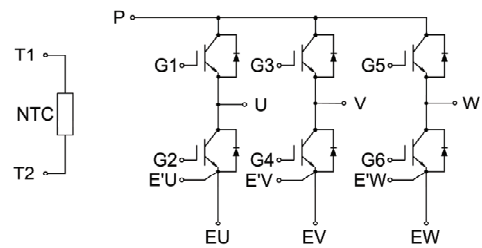
## IGBT Module

Preliminary Data

### Features:

- Trench & Field Stop IGBT
- Short Circuit Rated >10 $\mu$ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested(2 $\times$ I<sub>c</sub>)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

### Circuit Diagram



### Applications:

- Motor Drives
- Air Conditioning
- Servo Drives
- UPS

### IGBT, Inverter

#### Maximum Rated Values (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>CES</sub>	Collector-Emitter Blocking Voltage	T <sub>J</sub> =25°C	1200	V
V <sub>GES</sub>	Gate-Emitter Voltage		±20	V
I <sub>C</sub>	Continuous Collector Current	T <sub>C</sub> =100°C	25	A
		T <sub>C</sub> =25°C	50	A
I <sub>CM</sub>	Repetitive Peak Collector Current	T <sub>J</sub> =175°C	50	A
t <sub>SC</sub>	Short Circuit Withstand Time		>10	μs
P <sub>D</sub>	Maximum Power Dissipation (IGBT)	T <sub>C</sub> =25°C T <sub>Jmax</sub> =175°C	279	W



## Electrical Characteristics of IGBT ( $T_C=25^\circ\text{C}$ unless otherwise specified)

### Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1\text{mA}$ , $V_{CE}=V_{GE}$	5.0	5.6	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=25\text{A}$ , $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	1.70	1.90	V
			$T_J=125^\circ\text{C}$	1.95		
			$T_J=150^\circ\text{C}$	2.00		
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$ , $V_{CE}=V_{CES}$ , $T_J=25^\circ\text{C}$			1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$ , $V_{CE}=0\text{V}$ , $T_J=25^\circ\text{C}$			200	nA
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=100\text{kHz}$		2.42		nF
$C_{oes}$	Output Capacitance			0.17		
$C_{res}$	Reverse Transfer Capacitance			0.02		

### Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}$ , $I_C=25\text{A}$ , $R_{Gon}=20\Omega$ , $V_{GE}=\pm 15\text{V}$ , Inductive Load	$T_J=25^\circ\text{C}$		102		ns
			$T_J=125^\circ\text{C}$		99		
			$T_J=150^\circ\text{C}$		99		
$t_r$	Rise Time		$T_J=25^\circ\text{C}$		39		ns
			$T_J=125^\circ\text{C}$		39		
			$T_J=150^\circ\text{C}$		37		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ\text{C}$		138		ns
			$T_J=125^\circ\text{C}$		147		
			$T_J=150^\circ\text{C}$		145		
$t_f$	Fall Time	$T_J=25^\circ\text{C}$		494		ns	
		$T_J=125^\circ\text{C}$		723			
		$T_J=150^\circ\text{C}$		728			
$E_{on}$	Turn-on Switching Loss	$V_{CC}=600\text{V}$ , $I_C=25\text{A}$ , $R_{Gon}=20\Omega$ , $V_{GE}=\pm 15\text{V}$ , $di/dt=548\text{A}/\mu\text{s}$ ( $T_J=150^\circ\text{C}$ ), Inductive Load	$T_J=25^\circ\text{C}$		2.14		mJ
		$T_J=125^\circ\text{C}$		2.76			
		$T_J=150^\circ\text{C}$		2.97			



E <sub>off</sub>	Turn-off Switching Loss	V <sub>CC</sub> =600V, I <sub>C</sub> =25A, R <sub>Goff</sub> =20Ω, V <sub>GE</sub> =±15V, du/dt=2299V/μs(T <sub>J</sub> =150°C), Inductive Load	T <sub>J</sub> =25°C	1.97	mJ
			T <sub>J</sub> =125°C	3.22	
			T <sub>J</sub> =150°C	3.54	
Q <sub>g</sub>	Total Gate Charge	V <sub>GE</sub> =+15V...-15V	T <sub>J</sub> =25°C	129	nC
RBSOA	I <sub>C</sub> =50A, V <sub>CC</sub> =1050V, V <sub>P</sub> =1200V, R <sub>Goff</sub> =20Ω, V <sub>GE</sub> =+15V to 0V, T <sub>J</sub> =150°C			Trapezoid	
I <sub>SC</sub>	V <sub>CC</sub> =600V, V <sub>GE</sub> = ±15V, tp=10us, R <sub>Gon</sub> =20Ω, R <sub>Goff</sub> =20Ω, T <sub>J</sub> =125°C			90	A
R <sub>θJC</sub>	IGBT Thermal Resistance: Junction-to-Case (per IGBT)			0.538	°C/W

## Diode, Inverter

### Maximum Rated Values (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	T <sub>J</sub> =25°C	1200	V
I <sub>F</sub>	Diode Continuous Forward Current		25	A
I <sub>FM</sub>	Diode Maximum Forward Current	tp=1ms	50	A

### Electrical Characteristics of FWD (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
V <sub>FM</sub>	Forward Voltage	I <sub>F</sub> =25A	T <sub>J</sub> =25°C	1.65		V
			T <sub>J</sub> =125°C	1.70		
			T <sub>J</sub> =150°C	1.70		
t <sub>rr</sub>	Reverse Recovery Time		T <sub>J</sub> =25°C	213		A
			T <sub>J</sub> =125°C	441		
			T <sub>J</sub> =150°C	458		
I <sub>rr</sub>	Peak Reverse Recovery Current	I <sub>F</sub> =25A, di/dt=695A/μs(T <sub>J</sub> =150°C), V <sub>rr</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	24.4		ns
			T <sub>J</sub> =125°C	29.1		
			T <sub>J</sub> =150°C	30.3		
Q <sub>rr</sub>	Reverse Recovery Charge		T <sub>J</sub> =25°C	2.60		μC
			T <sub>J</sub> =125°C	4.97		
			T <sub>J</sub> =150°C	5.52		



E <sub>rec</sub>	Reverse Recovery Energy	I <sub>F</sub> =25A, di/dt=695A/μs(T <sub>J</sub> =150°C), V <sub>rr</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	0.85	mJ
			T <sub>J</sub> =125°C	1.95	
			T <sub>J</sub> =150°C	2.18	
R <sub>θJC</sub>	Diode Thermal Resistance: Junction-to-Case (per Diode)			0.693	°C/W

### Internal NTC-Thermistor Characteristics

Symbol	Description		Min.	Typ.	Max.	Units.
R <sub>25</sub>	Rated Resistance	T <sub>C</sub> =25°C		5		kΩ
ΔR/R	Deviation of R100	T <sub>C</sub> =100°C, R <sub>100</sub> =481Ω			±5	%
P <sub>25</sub>	Power Dissipation	T <sub>C</sub> =25°C		10		mW
B <sub>25/50</sub>	B-Value	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$		3380		K
B <sub>25/80</sub>	B-Value	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$		3440		K
B <sub>25/100</sub>	B-Value	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15K))]$		3545		K



## Module

Symbol	Description	Min.	Typ.	Max.	Units	
V <sub>IOS</sub>	Isolation Voltage (All Terminals Shorted)	RMS, 50Hz, t=30s		4500	V	
Internal Isolation		Al <sub>2</sub> O <sub>3</sub>				
L <sub>SCE</sub>	Stray Inductance Module		25		nH	
T <sub>J</sub>	Maximum Junction Temperature			175	°C	
T <sub>JOP</sub>	Maximum Operating Junction Temperature Range	-40		+150	°C	
T <sub>stg</sub>	Storage Temperature	-40		+125	°C	
CTI	Comparative Tracking Index	200				
R <sub>ecs</sub>	Case-to-Sink Thermally (Conductive Grease Applied)			0.08	°C/W	
M	Mounting Torque for solder pins Module Mounting	Screw M4--Mounting according to valid application note		1.5	1.8	N·m
	Mounting Torque for press-fit pins Module Mounting	Screw M4--Mounting according to valid application note		0.75	1.2	N·m
G	Weight		23		g	

## Ordering Information Table

Device code

G	T	25	FF	120	B3	H
①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench, Low Switching Losses IGBT
- ③ - Rated Current (25=25A)
- ④ - Circuit Configuration (FF=Full Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

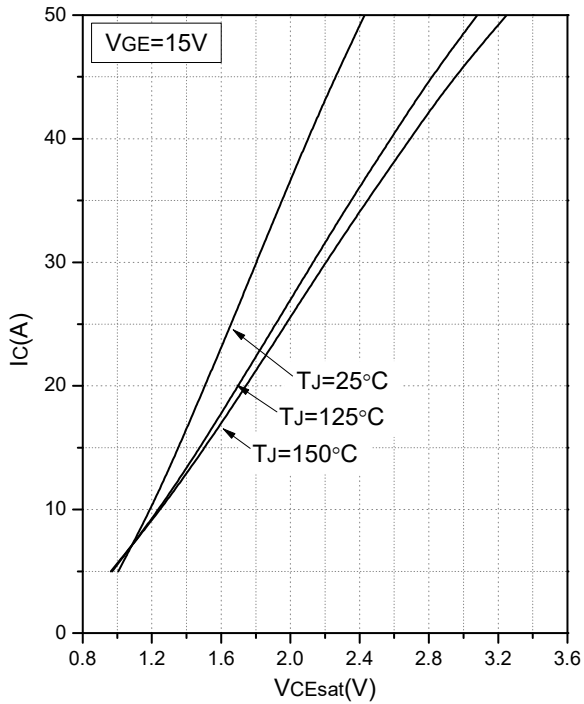


Fig.1 Typical Saturation Voltage Characteristics

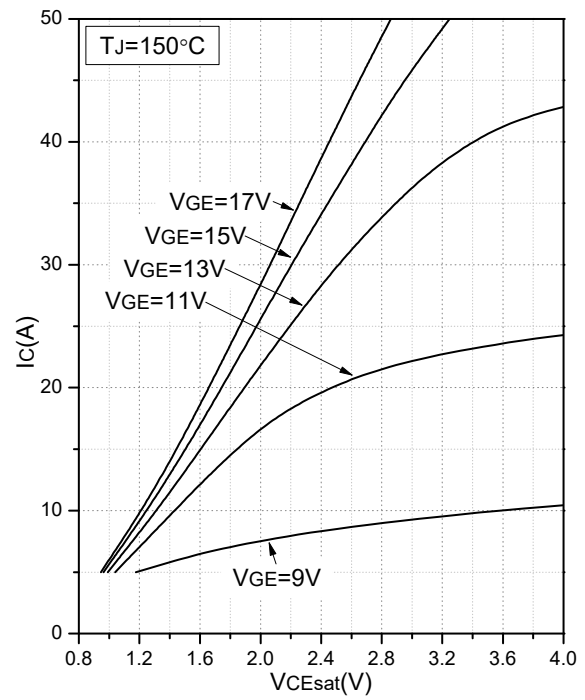


Fig.2 Typical Output Characteristics

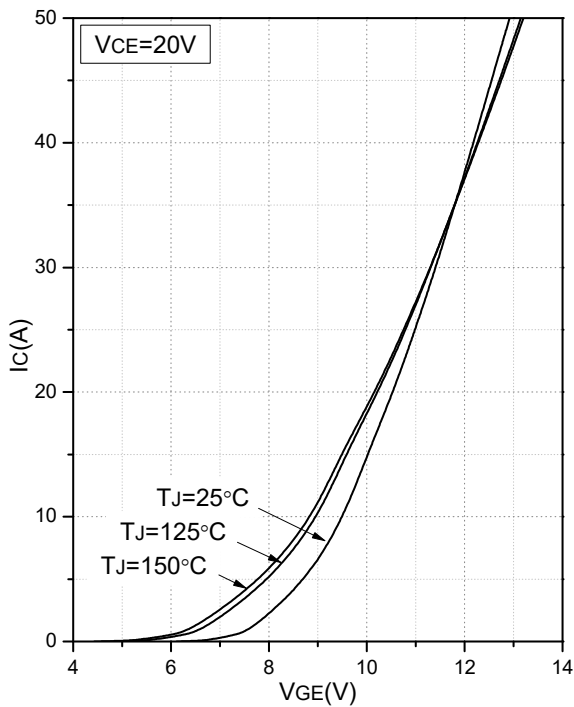


Fig.3 Transfer Characteristic

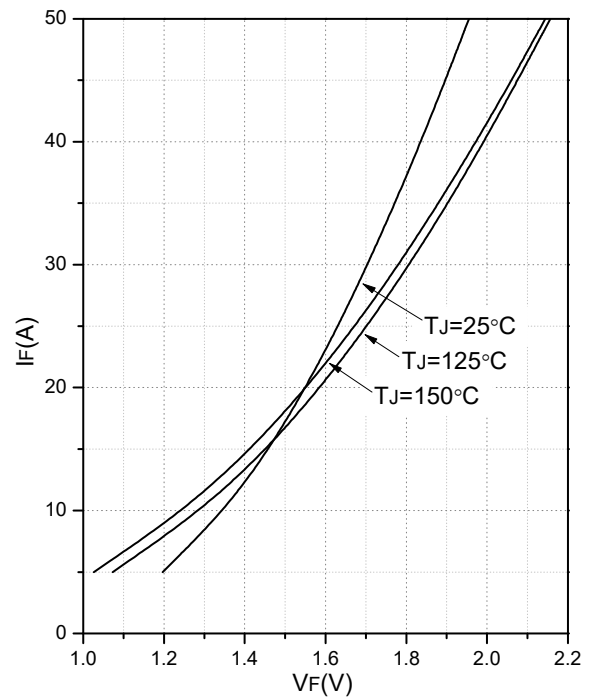


Fig.4 Forward Characteristics of FWD

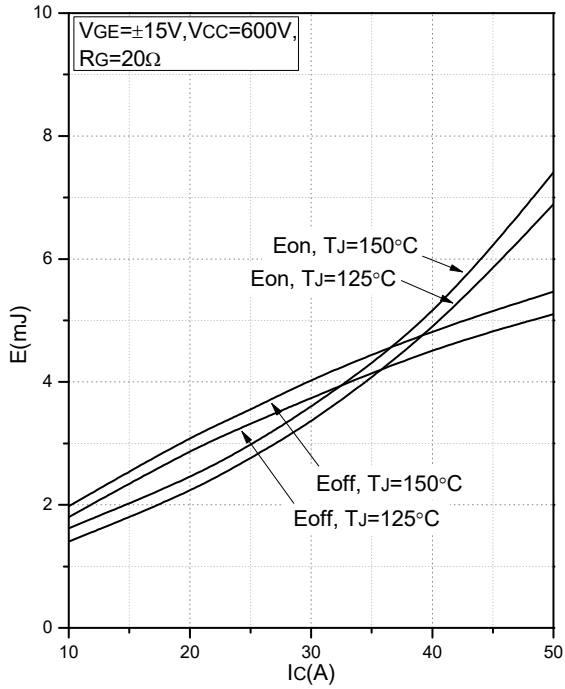


Fig.5 Typical Switching Loss vs. Collector Current

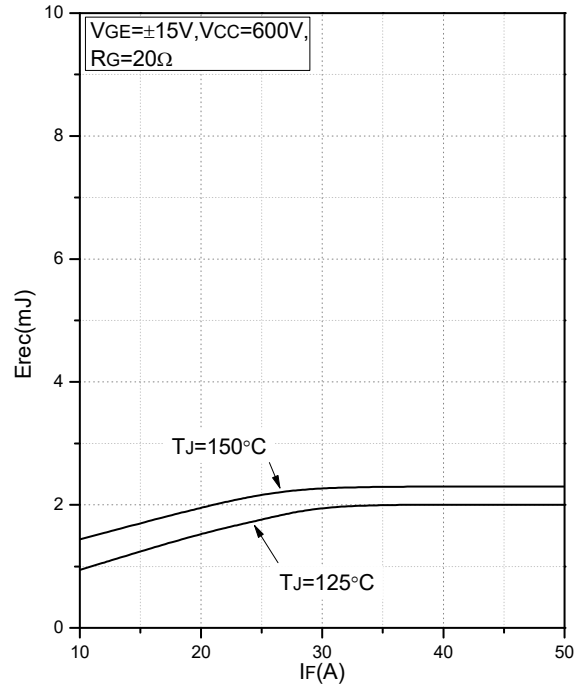


Fig.6 Typical Switching Loss vs. Forward Current

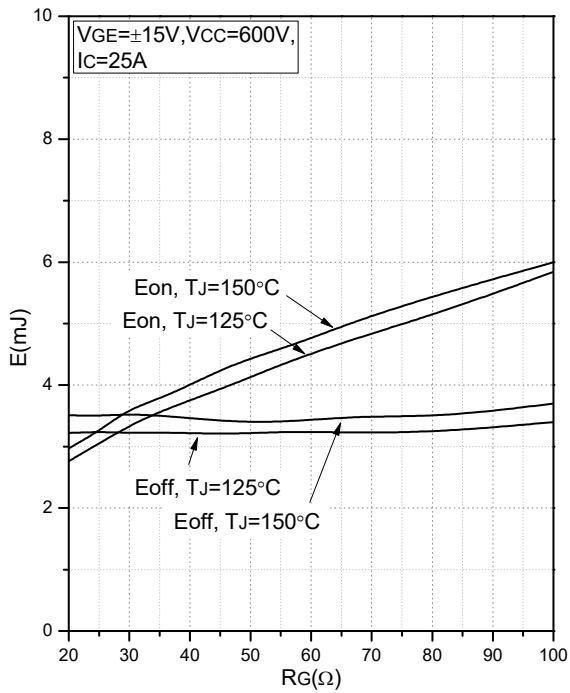


Fig.7 Typical Switching Loss vs. Gate Resistance

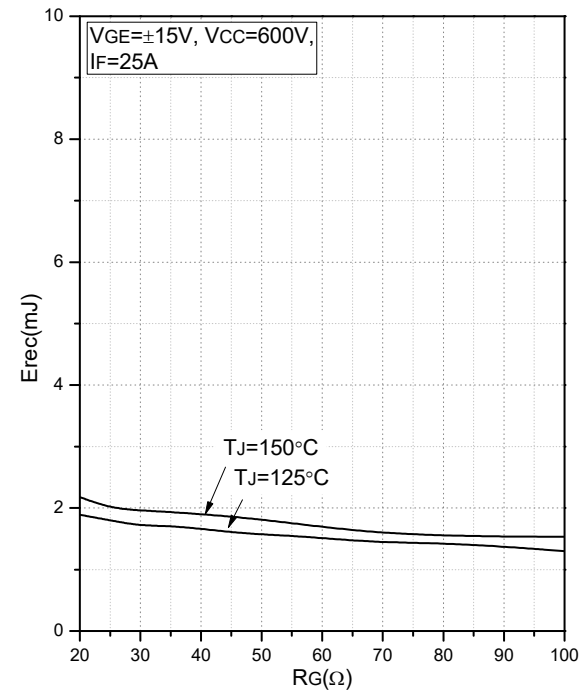


Fig.8 Typical Switching Loss vs. Gate Resistance

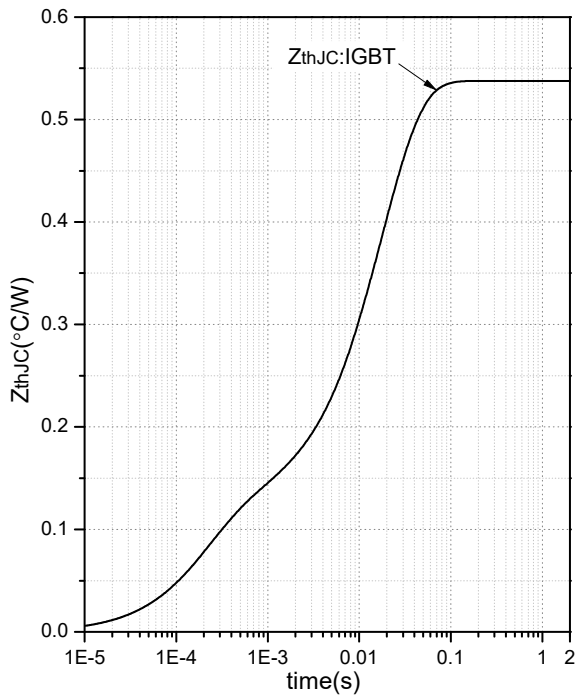


Fig.9 Transient Thermal Impedance (IGBT)

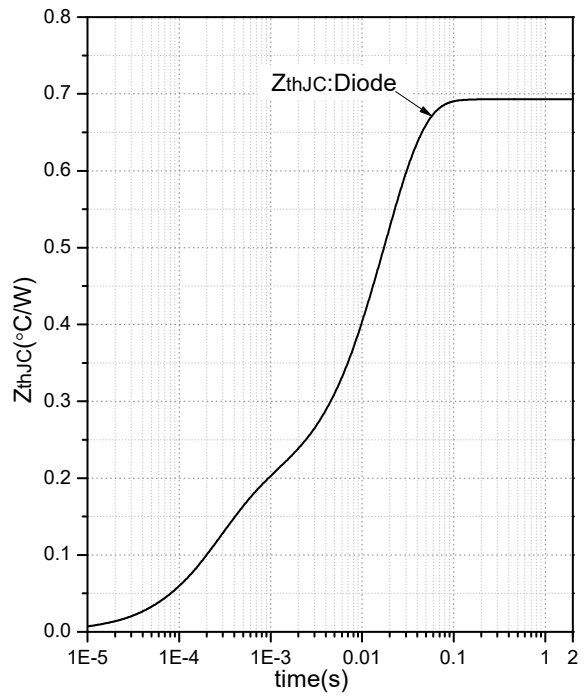


Fig.10 Transient Thermal Impedance (Diode)

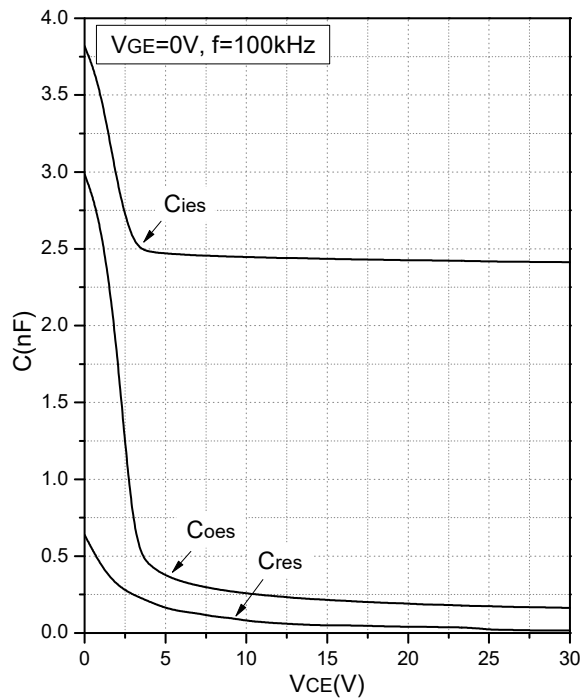


Fig.11 Capacitance Characteristics

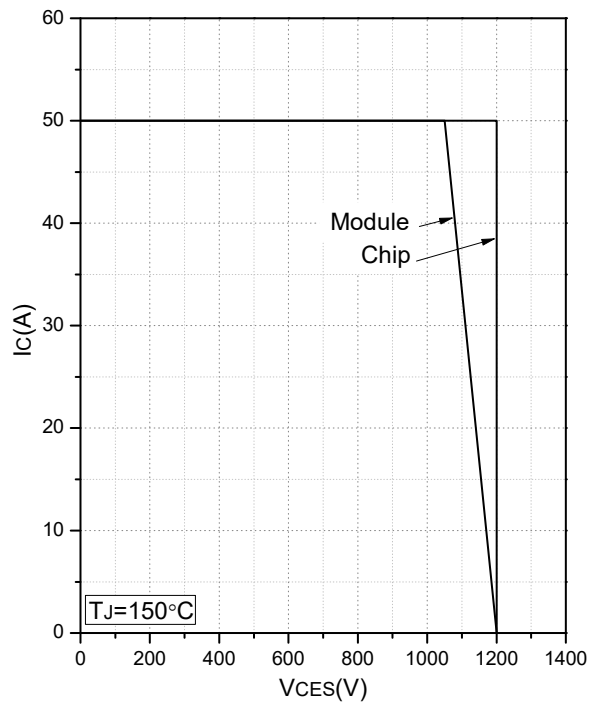


Fig.12 Reverse Bias Safe Operation Area (RBSOA)



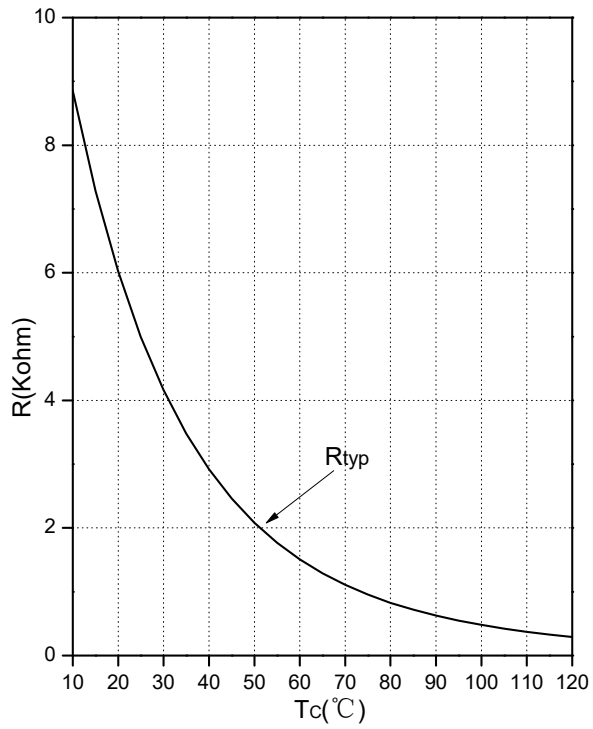
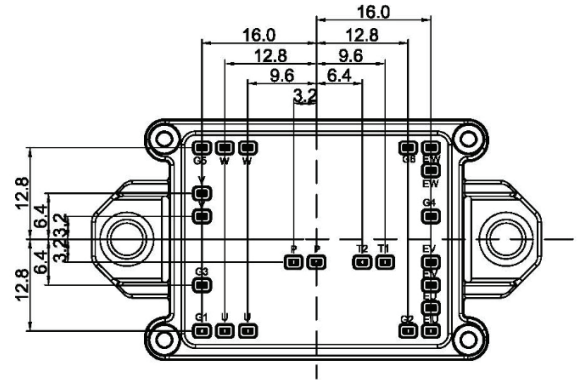
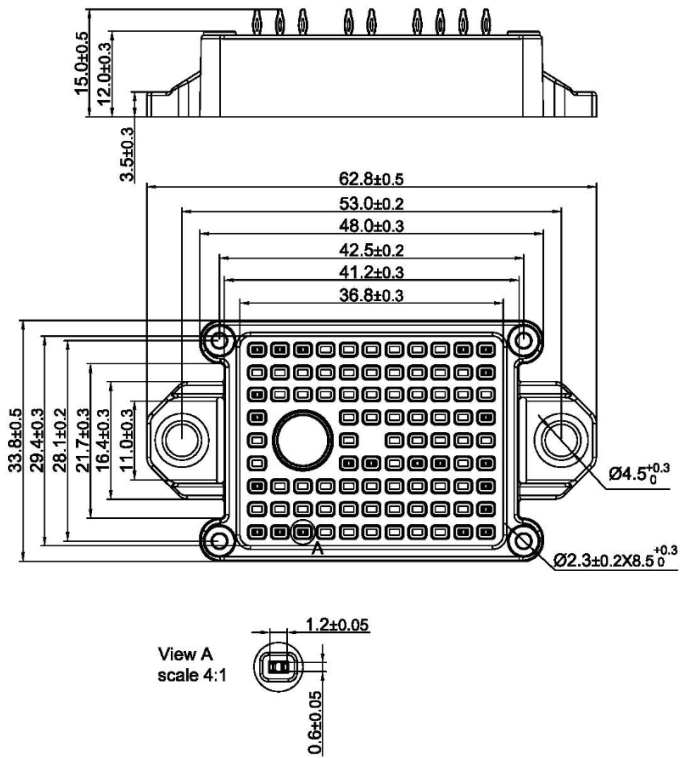


Fig.13 NTC Temperature Characteristics





Pins type II--Press-fit pins





Date	Revision	Notes
08/24/2023	01	Initial Release

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